

Title (en)

INJECTION MOLDING USING A COMPOSITE STRUCTURE INSERT WITHIN THE MOLDING CAVITY

Title (de)

SPRITZGIESSEN UNTER VERWENDUNG EINES VERBUNDSTRUKTUREINSATZES IN DEM FORMWERKZEUG

Title (fr)

MOULAGE PAR INJECTION UTILISANT UN INSERT A STRUCTURE COMPOSITE DANS LA CAVITE DE MOULAGE

Publication

**EP 0888207 A1 19990107 (EN)**

Application

**EP 97953204 A 19971219**

Priority

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- US 77279696 A 19961224

Abstract (en)

[origin: WO9828120A1] An injection molded reinforced structure (20) is prepared by providing an injection mold (40) having an injection molding cavity (42), and preparing a freestanding injection-mold insert (60) conforming to at least a portion of the shape of the injection molding cavity (42). The insert (60) preferably is formed of reinforcing fibers embedded in an insert thermoplastic resin matrix. The insert (60) is placed into the injection molding cavity (42), and an injection thermoplastic resin is injected into the injection molding cavity (42) and thence around the insert (60), thereby forming the injection molded reinforced composite structure (20).

IPC 1-7

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IPC 8 full level

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CPC (source: EP US)

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